

Component	Weight (mg)	Type	Material	CAS#	%	Weight (mg)	PPM of Total Weight
Chip	9.947	159x160x10 mils	Silicon	7440-21-3	100.00	9.947	54858.734
Lead Frame	79.408	C7025	Copper	7440-50-8	96.20	74.834	412716.247
			Ni	7440-02-0	3.00	2.334	12870.569
			Si	7440-21-3	0.65	0.506	2788.623
			Mg	7439-95-4	0.15	0.117	643.528
		Ag	Silver	7440-22-4	100.00	1.618	8923.413
Mold Compound	86.394	SUMIKON EMEG700LX	Silica Fused	60676-86-0	87.50	75.595	416910.199
			Epoxy Resin	Trade Secret	4.00	3.456	19058.752
			Phenol Resin	Trade Secret	8.00	6.912	38117.504
			Carbon Black	1333-86-4	0.50	0.432	2382.344
Bonding Wire	1.170	Wire Dia : 1 mils	Au	7440-57-5	99.99	1.170	6453.024
			Dopant	-	0.01	0.000	0.645
Epoxy	1.502	CRM 1076DF	Silver (Ag)	7440-22-4	74.50	1.119	6170.598
			Epoxy Resin A	9003-36-5	11.50	0.173	952.508
			t-Butyl phenyl glycidyl ether	3101-60-8	7.50	0.113	621.201
			Butyl Cellosolve acetate	112-07-2	1.50	0.023	124.240
			Hardener	620-92-8	1.50	0.023	124.240
			1,1,1-Tris(p-hydroxyphenyl) ethane	27955-94-8	3.50	0.053	289.894
Plating	2.900	LEAD FREE Sn 100%	Sn	7440-31-5	99.987	2.900	15991.657
			Pb	7439-92-1	0.005	0.000	0.800
			Cu	7440-50-8	0.003	0.000	0.480
			Cd	7440-43-9	0.001	0.000	0.160
			Bi	7440-69-9	0.003	0.000	0.480
			Sb	7440-36-0	0.001	0.000	0.160
Total Weight	181.321					181.321	1000000.000